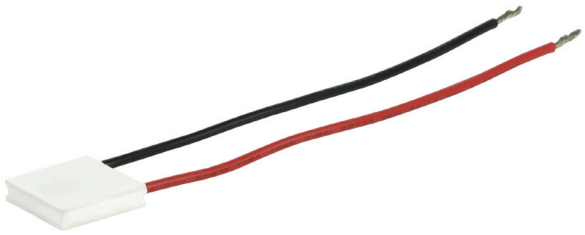
SERIES: CP08-M | DESCRIPTION: PELTIER MODULE

FEATURES

- solid state device
- micro size
- precise temperature control
- quiet operation



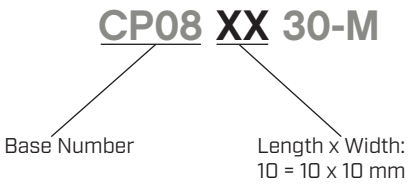
RoHS

MODEL

MODEL	input voltage[1] max (Vdc)	input current[2] max (A)	output Qmax[3] T_h=27°C (W)	output Qmax[3] T_h=50°C (W)	output ΔTmax[4] T_h=27°C (°C)	output ΔTmax[4] T_h=50°C (°C)
CP081030-M	8.8	0.8	3.7	4.2	68	75

Notes:
1. Maximum voltage at ΔT max and T_h=27°C
2. Maximum current to achieve ΔT max
3. Maximum heat absorbed at cold side occurs at I_{max}, V_{max}, and ΔT=0°C
4. Maximum temperature difference occurs at I_{max}, V_{max}, and Q=0W (ΔT max measured in a vacuum at 1.3 Pa)

PART NUMBER KEY



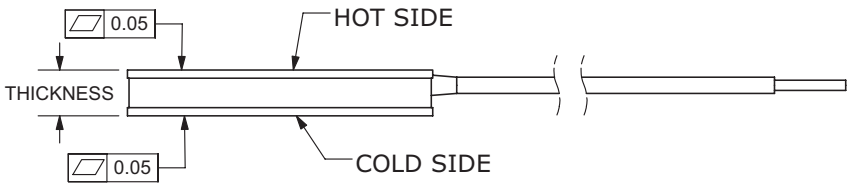
SPECIFICATIONS

parameter	conditions/description	min	typ	max	units
internal resistance[1]		8.865	9.85	10.835	Ω
solder melting temperature	connection between thermoelectric pairs	235			°C
assembly compression				0.8	MPa
hot side plate				80	°C
RoHS	yes				

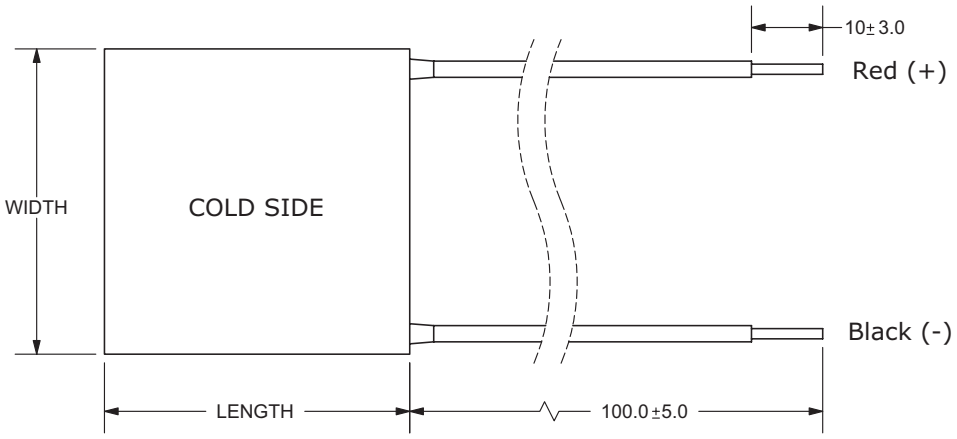
Note: 1. Measured by AC 4-terminal method at 25°C

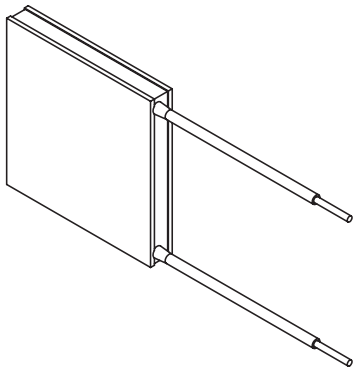
MECHANICAL DRAWING

units: mm



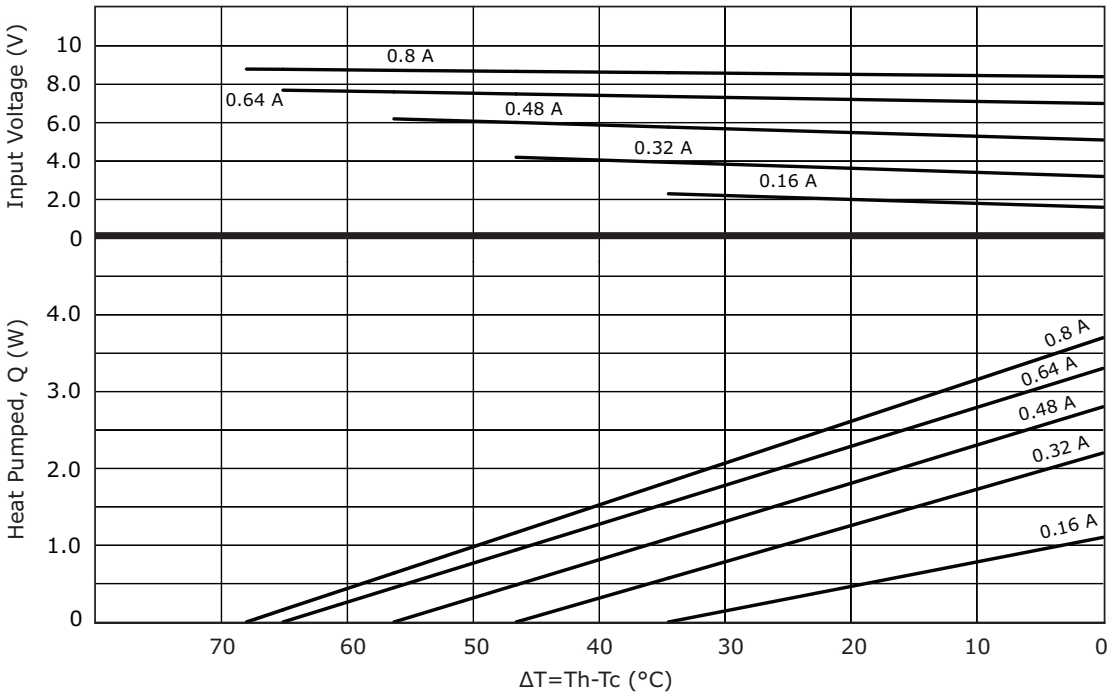
	MATERIAL	PLATING
ceramic plate	96% AL_2O_3	
wire leads	28 AWG	tin
sealer	silicon rubber 703 RTV (between cold and hot side plates)	
joint cover	silicon rubber 703 RTV	
marking	P/N & S/N printed on cold side surface	



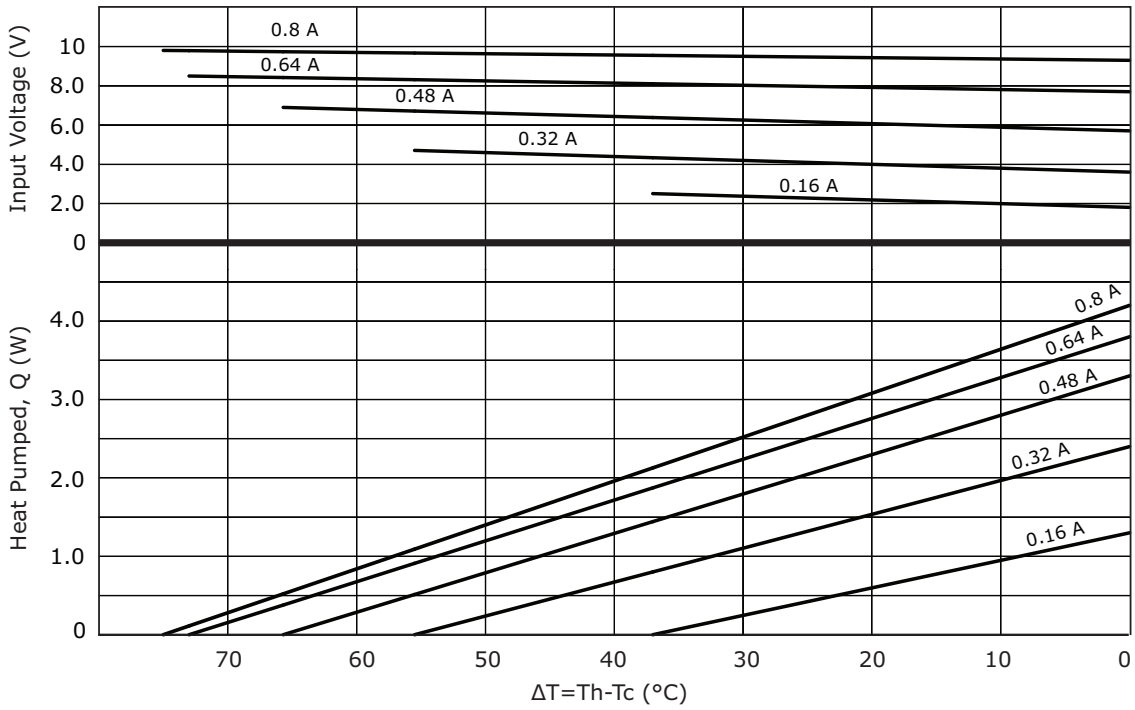


MODEL NO.	LENGTH (mm)	WIDTH (mm)	THICKNESS (mm)
CP081030-M	10 ±0.3	10 ±0.3	3.0 ±0.1

PERFORMANCE (Th=27°C)



PERFORMANCE (Th=50°C)



REVISION HISTORY

rev.	description	date
1.0	initial release	09/08/2016
1.01	brand update	10/28/2019
1.02	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.